

**SPECIFICATION AMENDMENTS:**

Please replace ¶[0026], with the following amended paragraph:

**[0026]**     Thereafter, a semiconductor chip 3 having a projection electrode (bump) 18 connected to an electrode of a ~~function~~ functional element 4 is prepared. The projection electrode 18 includes a solder material.

Please replace ¶[0028], with the following amended paragraph:

**[0028]**     Thereafter, the projection electrode 18 of the semiconductor chip 3 is positionally adjusted for the contact with a connection pad 16 of the substrate 15, whereafter the bonding tool 19 is lowered so as to bond the semiconductor chip 3 with the substrate 15. In this case, the semiconductor chip 3 is heated by the bonding tool 19, and the solder material of the projection electrode 18 is melted by that heat, whereby the projection electrode 18 and the connection pad 16 are bonded together. As a result, the connecting member 5 by which the substrate 15 and the semiconductor chip 3 are mechanically bonded together is formed. The wiring formed on the surface 15a of the substrate 15 is electrically connected to the ~~function~~ functional element 4 of the semiconductor chip 3 by means of the connecting member 5. As shown in FIG. 1, the functional element 4 is not formed

in an end portion or periphery of the functional surface **3a** of the semiconductor chip **3**, so functional element **4** is not formed on an entirety of the functional surface of the semiconductor chip.